

PATENT ASSIGNMENT

Electronic Version v1.1

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
Jelena H. Larsen	04/04/2006
Chee Kiong Fong	04/04/2006
Peter Anthony Atkinson	04/10/2006
Raul Rodriguez-Montanez	04/04/2006
RECEIVING PARTY DATA	
Name:	Microsoft Corporation
Street Address:	One Microsoft Way
City:	Redmond
State/Country:	WASHINGTON
Postal Code:	98052
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	11344276
CORRESPONDENCE DATA	
Fax Number:	(425)708-5046
<i>Correspondence will be sent via US Mail when the fax attempt is unsuccessful.</i>	
Phone:	(425) 705-4630
Email:	p5sup@microsoft.com
Correspondent Name:	Rimma N. Oks
Address Line 1:	One Microsoft Way
Address Line 4:	Redmond, WASHINGTON 98052
ATTORNEY DOCKET NUMBER:	313960.01
NAME OF SUBMITTER:	Rimma N. Oks
Total Attachments: 4	
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I/WE, Jelena H. Larsen, Chee Kiong Fong, Peter Anthony Atkinson, and Raul Rodriguez-Montanez ("ASSIGNOR"), have invented subject matter ("INVENTION") disclosed and/or claimed in a patent application entitled "HIGH DENSITY SURFACE MOUNT PART ARRAY LAYOUT AND ASSEMBLY TECHNIQUE" ("APPLICATION"), which:

- ☐ will be filed without this executed PATENT ASSIGNMENT. ASSIGNOR hereby authorizes, and requests, ASSIGNEE'S legal representatives, of the Law and Corporate Affairs Department, Microsoft Corporation, One Microsoft Way, Redmond, Washington 98052, who are associated with customer number 22971, to insert here in parenthesis (Application No. _____, filed _____) this APPLICATION's Application No. and filing date, when known;
- ☒ was filed on 01/31/2006 and was given Application No. 11/344,276;
- ☐ is filed concurrently herewith;

Microsoft Corporation, a Washington Corporation, on behalf of itself and its successors and assigns ("ASSIGNEE"), is entitled to, and is desirous of acquiring, the entire and exclusive rights, title and interest in the INVENTION and the APPLICATION (and all other applications and patents derived therefrom, such as continuing applications, in and for the United States, its territories, and all foreign countries ("APPLICATION DERIVATIVES"));

For good and valuable consideration, the receipt of which is hereby acknowledged by the ASSIGNOR, the ASSIGNOR hereby sells, assigns and transfers to the ASSIGNEE, the entire and exclusive rights, title and interest in the INVENTION and the APPLICATION (and APPLICATION DERIVATIVES);

ASSIGNOR agrees to execute all instruments and documents required for the making and prosecution of the APPLICATION (and APPLICATION DERIVATIVES), for litigation regarding letters patent derived therefrom, and for the purpose of protecting and perfecting title to the APPLICATION (and APPLICATION DERIVATIVES).

04-04-06
Date

Jelena H. Larsen
Jelena H. Larsen

Date

Chee Kiong Fong

Date

Peter Anthony Atkinson

Date

Raul Rodriguez-Montanez

PATENT ASSIGNMENT

MS Docket No.: 313960.01

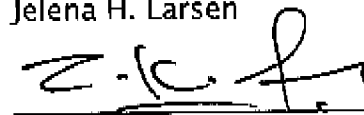
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Date4/4/06_____
Date_____
Jelena H. Larsen_____
Chee Kiong Fong_____
Date_____
Peter Anthony Atkinson_____
Date_____
Raul Rodriguez-Montanez

PATENT ASSIGNMENT

MS Docket No.: 313960.01

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Chee Kiong Fong4/10/2006
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